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MODEL VERSION:	00					
SPEC VERSION:	V2.4					
ISSUED DATE:	2015.12.04					
□Preliminary Specification ■Final Product Specification						

Customer :_____

Approved by	Notes

TIANMA Confirmed:

Prepared by	Checked by	Approved by		
Lynn. Fu	Flexi. Tan	Qing.F.en		
2015.12.04	2015.12.04	2015.12.04		

This technical specification is subjected to change without notice



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Record of Revision

Rev	Issued Date	Description	Editor
1.0	2014-04-10	Preliminary Specification Release	Wenlong Liu
1.1	2014-04-28	Modify the mistake of RA test requirements	Yihua_liang
2.0	2014-09-05	Final Product Release. change mechanical drawing, optical characteristics	Wenlong Liu
2.1	2014-09-30	Add Packing Drawing	Wenlong Liu
2.2	2015-08-31	Update Packing Drawing and VCI MIN. value	wuxuan
2.3	2015-10-26	Modify SPI Interface Timing Characteristic (Page16 17), update packing	Lynn. Fu
2.4	2015-12-04	Add lifetime and update packing	Lynn. Fu



1 General Specifications

	Feature	Spec		
	Size	3.5 inch		
	Resolution	320(RGB) x 480		
	Technology Type	a-Si		
	Pixel Configuration	R.G.B. Vertical Stripe		
Display Spec.	Pixel pitch(mm)	0.153(H)x0.153(V)		
	Display Mode	TM with Normally White		
	Surface Treatment	HC		
	Viewing Direction	6 o'clock		
	Gray Scale Inversion Direction	12 o'clock		
	LCM (W x H x D) (mm)	55.26 x 84.69 x 2.2		
	Active Area(mm)	48.96x73.44		
Mechanical	With /Without TSP	Without TSP		
Characteristics	Matching Connection Type	ZIF		
	LED Numbers	6 LEDs		
	Weight (g)	21.0		
Flactoinal	Interface	MCU+RGB+SPI		
Electrical Characteristics	Color Depth	65K/262K		
Onal acteristics	Driver IC	ILI9488		

Note 1: Viewing direction for best image quality is different from TFT definition. There is a 180 degree shift.

Note 2: Requirements on Environmental Protection: Q/S0002+HF

Note 3: LCM weight tolerance: ± 5%



2 Input/Output Terminals

Pin No.	Symbol	I/O	Function	Remark
1	FLM	0	Output a frame head pulse signal If no used, please open this pin	
2	GND	Р	Ground	
3	ENABLE	I	Data enable signal in RGB mode If no used, please fix this pin at GND level	
4	DOTCLK	I	Pixel clock signal in RGB mode If no used, please connect this pin to GND	
5	VSYNC	I	Vertical sync. signal in RGB mode If no used, please connect this pin to GND	
6	GND	Р	Ground	
7	HSYNC	I	Horizontal sync, signal in RGB mode If no used, please connect this pin to GND	
8	IMO	I	MPU system interface mode select	
9	IM1	I	MPU system interface mode select	
10	IM2	I	MPU system interface mode select	
11	IOVCC	р	IO POWER	
12	VCC	Р	Analog POWER	
13	SDI	I/O	Serial data in/out pin in DBI Type C 9bit mode Serial data input pin in DBI Type B 8bit mode If no used, please connect this pin to GND	
14	SDO	0	Serial data output pin If no used, leave this pin open	
15	DB17	I/O	Data Bus	
16	DB16	I/O	Data Bus	
17	DB15	I/O	Data Bus	
18	DB14	I/O	Data Bus	
19	DB13	I/O	Data Bus	
20	DB12	I/O	Data Bus	
21	DB11	I/O	Data Bus	
22	DB10	I/O	Data Bus	
23	DB9	I/O	Data Bus	
24	DB8	I/O	Data Bus	
25	DB7	I/O	Data Bus	
26	DB6	I/O	Data Bus	
27	DB5	I/O	Data Bus	



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28	DB4	I/O	Data Bus
29	DB3	I/O	Data Bus
30	DB2	I/O	Data Bus
31	DB1	I/O	Data Bus
32	DB0	I/O	Data Bus
33	RESET	I	Reset pin
34	RD	I	Read strobe signal If no used, please connect this pin to IOVCC
35	WR/SCL	I	(WR) Write data enable pin in DBI Type B (SCL) Write data enable pin in DBI Type C If no used, please connect this pin to IOVCC
36	RS	I	Data/command selection pin If no used, please connect this pin to IOVCC
37	CS		Chip select signal If no used, please connect this pin to IOVCC
38	LEDK6	Р	LED CATHODE
39	LEDK5	Р	LED CATHODE
40	LEDK4	Р	LED CATHODE
41	LEDK3	Р	LED CATHODE
42	LEDK2	Р	LED CATHODE
43	LEDK1	Р	LED CATHODE
44	LEDA	Р	LED ANODE
45	LCM_ID	0	Customer requirement: 1.8V

Note1: I/O definition: I----Input O---Output P----Power/ Ground NC---Not Connected

IM2	IM1	IM0	Interface	WR/SCL	DATA Bus use		
					Command/Parament	GRAM	
0	0	0	DBITYPE-B18-bit (DB_EN='0')	WR	DB7-DB0	DB17-DB0:18bits Data	
0	0	1	DBI TYPE-B 9-bit	WR	DB7-DB0	DB8-DB0:9bits Data	
0	1	0	DBI TYPE-B 16-bit	WR	DB7-DB0	DB15-DB0:16bits Data	
0	1	1	DBI TYPE-B 8-bit	WR	DB7-DB0	DB7-DB0:8bits Data	
1	0	1	DBI TYPE-C Option 1(3 wire)	SCL	SDA/SDO		
1	1	1	DBI TYPE-C Option 3(4 wire)	SCL	SDA/SDO		

Table 2.1 System interface select



3 Absolute Maximum Ratings

GND=0V

Item	Symbol	MIN	MAX	Unit	Remark
Power Voltage	VCI	-0.3	3.3	V	Neted
Logic supply voltage	IOVCC	-0.3	3.3	V	Note1
Logic Input voltage	RESET,CSX,SCL, SDA,D/CX	-0.3	IOVCC+0.3	V	
Operating Temperature	Тор	-20	70	$^{\circ}$	
Storage Temperature	Tst	-30	80	$^{\circ}$	
			≪95	%	Ta≤40°C
Data Constitues Silver			≤85	%	40°C < Ta ≤ 50°C
Relative Humidity Note2	RH		≤55	%	50°C <ta≤60°c< td=""></ta≤60°c<>
NOIGZ			≤36	%	60°C < Ta ≤ 70°C
			≪24	%	70℃ <ta≤80℃< td=""></ta≤80℃<>
Absolute Humidity	AH		≤70	g/m³	Ta>70℃

Table 3.1 Absolute Maximum Ratings

Note1: Input voltage include DB0~DB17, Dotclk, Hsync, Vsync, Enable, RESET, CS, RD, WR/SCL, LCM_ID etc(For your reference)

Note2: Ta means the ambient temperature.

It is necessary to limit the relative humidity to the specified temperature range. Condensation on the module is not allowed.



4 Electrical Characteristics

4.1 LCD module

Ta=25°C

I	tem	Symbol	MIN	TYP	MAX	Unit	Remark
_	gnal Input Voltage	IOVCC	1.65	1.8	3.3	٧	
Power S Voltage	Supply	VCI	2.65	2.8	3.3	V	
Input Signal	High Level	VIH	0.7*IOVCC	-	IOVCC	V	RESET,CSX,SCL,SDA,D/CX
Voltage	Low Level	VIL	-0.3	ı	0.3*IOVCC	>	112021100111001110111111111111111111111
Output Signal	High Level	VOH	0.8*IOVCC	ı	IOVCC	V	
_	Low Level	VOL	0	ı	0.2*IOVCC	٧	
(Panel+LSI)		Black Mode	ı	34.2	-	mW	
Power Consumption		Sleeping Mode	-	2.4	-	mW	

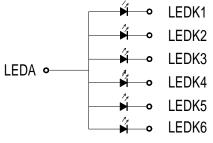
Table 4.1 LCD module electrical characteristics

4.2 Backlight Unit

Ta=25°C

Item	Symbol	Min	Тур	Max	Unit	Remark
Forward Current	I _F	-	20	-	mA	1 LED
Forward Voltage	V_{F}	-	3.2	-	V	1 LED
Backlight Power Consumption	W_{BL}	-	384	-	mW	6 LEDs in parallel
LED lifetime			30,000		hrs	

Note1: Figure below shows the connection of backlight LED.



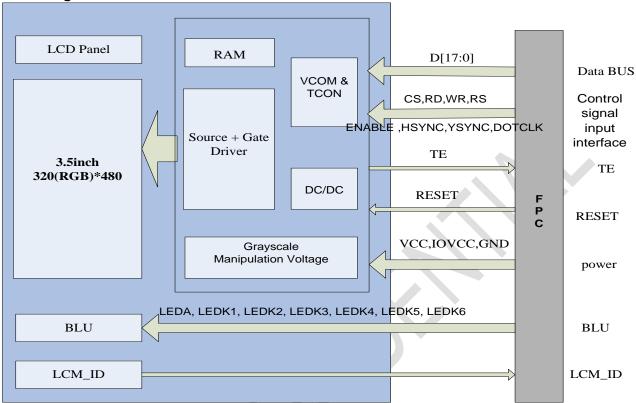
Note 2: 1LED: $V_F = 3.2V$ $I_F = 20mA$ Note 3: I_F is defined for one LED.

Optical performance should be evaluated at Ta=25 °C only.

If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.



4.3 Block Diagram

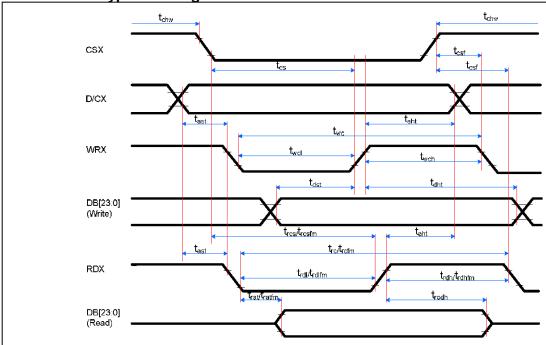




5 Timing Chart

5.1 DBI Type B

5.1.1 DBI Type B Timing Characteristic

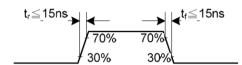


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	-
DCX	that	Address hold time (Write/Read)	0	-	ns	-
	tchw	CSX "H" pulse width	0	-	ns	=
	tcs	Chip Select setup time (Write)	15	-	ns	-
CSX	tros	Chip Select setup time (Read ID)	45	-	ns	=
	trosfm	Chip Select setup time (Read FM)	355	-	ns	-
	tesf	Chip Select Wait time (Write/Read)	0	-	ns	-
	twc	Write cycle	40	-	ns	-
WRX	twrh	Write Control pulse H duration	15	-	ns	-
	twrl	Write Control pulse L duration	15	-	ns	-
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	When read from Frame Memory
	trdlfm	Read Control L duration (FM)	355	-	ns	Wemory
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	When read ID data
	trdl	Read Control pulse L duration	45	-	ns	
DB [23:0],	tdst	Write data setup time	10	-	ns	
DB [23:0], DB [17:0],	tdht	Write data hold time	10	-	ns	
DB [15:0],	trat	Read access time	-	40	ns	For maximum, CL=30pF For minimum, CL=8pF
DB [8:0],	tratfm	Read access time	-	340	ns	Torminimum, GL=opF
DB [7:0]	trod	Read output disable time	20	80	ns	

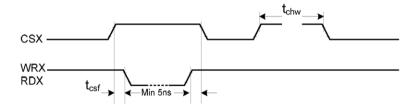


Notes

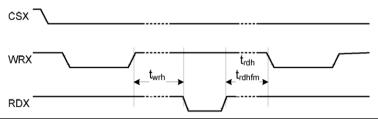
- 1. Ta = -30 to 70 $^{\circ}$ C, IOVCC = 1.65V to 3.3V, VCI = 2.5V to 3.3V, AGND = DGND = 0V
- 2. Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.
- 3. Input signal rising time and falling time:



4. The CSX timing:

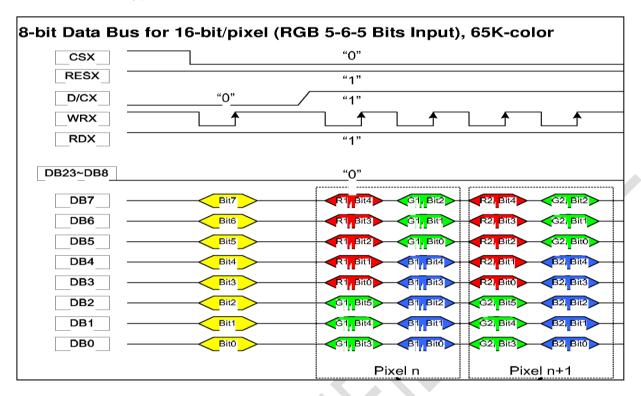


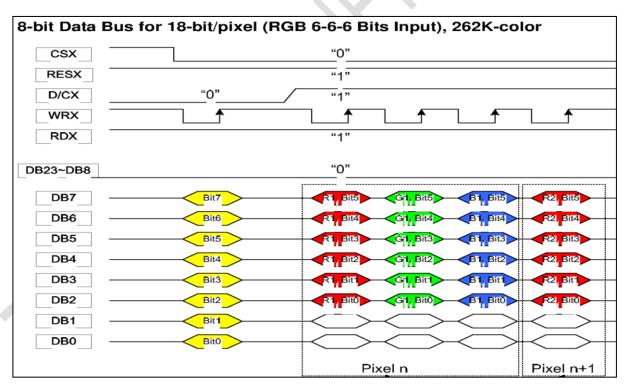
5. The Write to Read or the Read to Write timing:



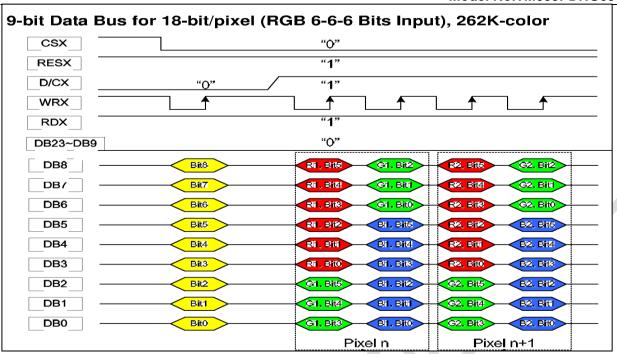


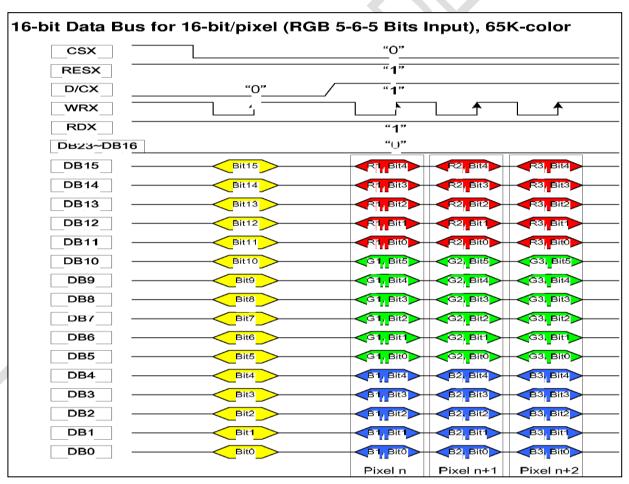
5.1.2 DBI Type B Data Bus





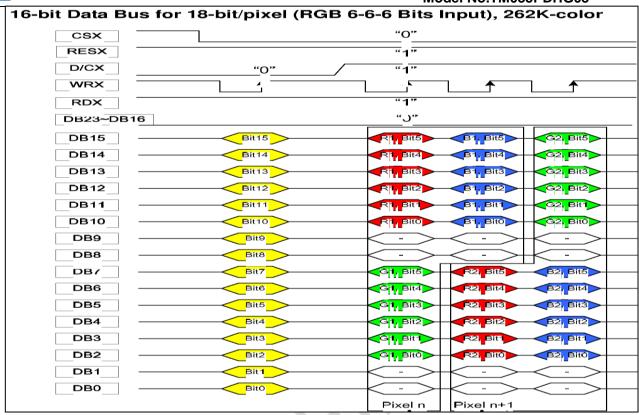


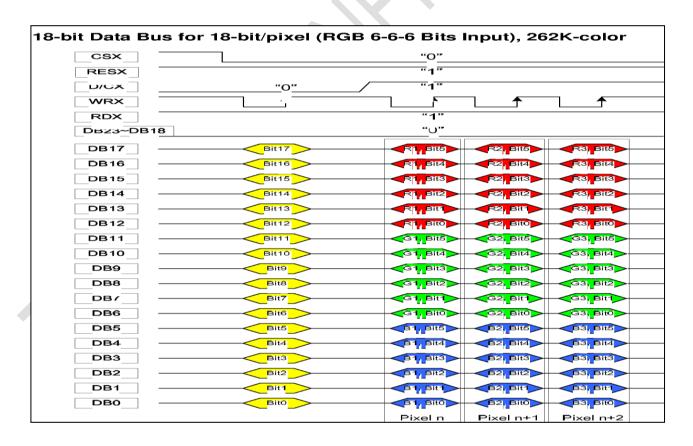






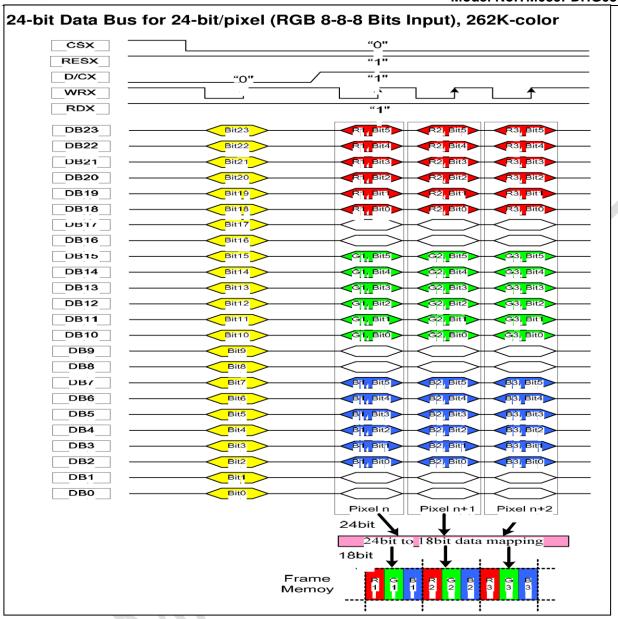






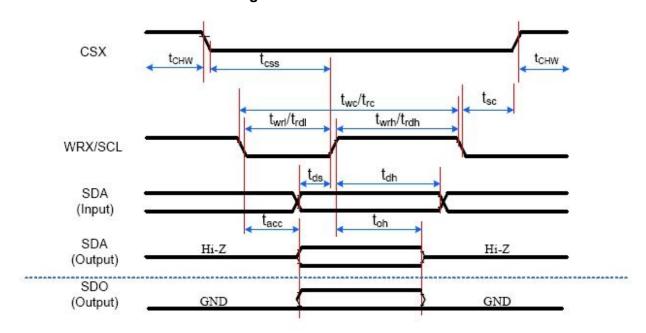






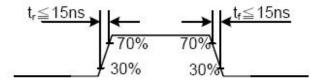


5.2 3-Line SPI Interface Timing Characteristic



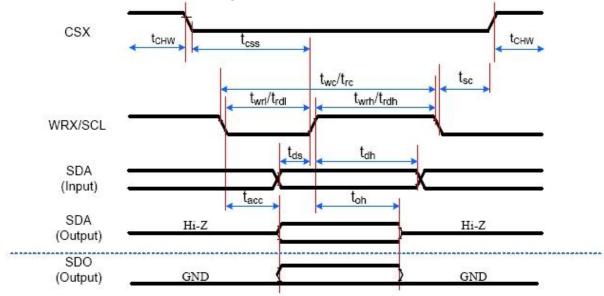
Signal	Symbol	Parameter	min	max	Unit	Description
2004	tsc	SCL-CSX	15	327.0	ns	
	tchw	CSX H Pulse Width	40	3723	ns	
CSX	tcss	Chip select time (Write)	60	327.0	ns	
	tcsh	Chip select hold time (Read)	65	3245	ns	
	twc	Serial Clock Cycle (Write)	66	0 22 5 0	ns	
	twrh	SCL H Pulse Width (Write)	15	690	ns	
SCL	twri	SCL L Pulse Width (Write)	15	0 050	ns	
SCL	trc	Serial Clock Cycle (Read)	150	680	ns	
	trdh	SCL H Pulse Width (Read)	60	0 050	ns	
	trdl	SCL L Pulse Width (Read)	60	690	ns	
SDA	tds	Data setup time (Write)	10	0 05:	ns	
(Input)	tdh	Data hold time (Write)	10	690	ns	
SDA/SDO	tacc	Access time (Read)	10	50	ns	For maximum CL=30pF
(Output)	toh	Output disable time (Read)	15	50	ns	For minimum CL=8pF

Note: Ta = -30 to 70 °C, IOVCC = 1.65V to 3.3V, VCI = 2.5V to 3.3V, AGND = DGND = 0V, T = 10+/-0.5ns



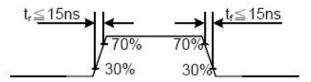


5.3 4-Line SPI Interface Timing Characteristic



Signal	Symbol	Parameter	min	max	Unit	Description
2004	tsc	SCL-CSX	15	275	ns	*
	tchw	CSX H Pulse Width	40	37 4 3	ns	
CSX	tcss	Chip select time (Write)	60	227.0	ns	
	tcsh	Chip select hold time (Read)	65	3740	ns	
	twc	Serial Clock Cycle (Write)	66	5 22 5 0	ns	
	twrh	SCL H Pulse Width (Write)	15	640	ns	
COL	twri	SCL L Pulse Width (Write)	15	0 - 05:	ns	
SCL	trc	Serial Clock Cycle (Read)	150	690	ns	
	trdh	SCL H Pulse Width (Read)	60	0 05:	ns	
	trdl	SCL L Pulse Width (Read)	60	690	ns	
SDA	tds	Data setup time (Write)	10	0 05:	ns	
(Input)	tdh	Data hold time (Write)	10	690	ns	
SDA/SDO (Output)	tacc	Access time (Read)	10	50	ns	For maximum CL=30pl
	toh	Output disable time (Read)	15	50	ns	For minimum CL=8pF

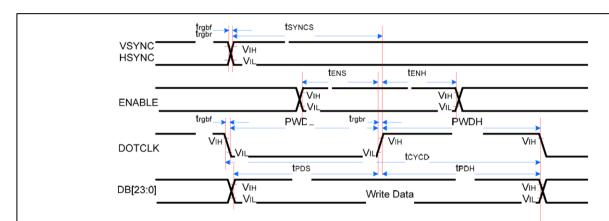
Note: Ta = -30 to 70 °C, IOVCC = 1.65V to 3.3V, VCI = 2.5V to 3.3V, AGND = DGND = 0V, T = 10+/-0.5ns





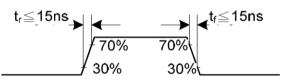
5.4 DPI Interface

5.4.1 DPI Interface Characteristic



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC/	t _{SYNCS}	VSYNC/HSYNC setup time		-	ns	
HSYNC	tsynch	VSYNC/HSYNC hold time	15	-	ns	
	t _{ENS}	ENABLE setup time	15	-	ns	
ENABLE	t _{ENH}	ENABLE hold time		-	ns	16-/18-/24-bit bus
	t _{POS}	Data setup time		-	ns	
DB [23:0]	t _{PDH}	Data hold time	15	-	ns	RGB interface mode
	PWDH	DOTCLK high-level period	20	-	ns	
	PWDL	DOTCLK low-level period	20	-	ns	
DOTCLK	t _{CYCD}	DOTCLK cycle time	50	-	ns	
	t _{rgbr} , t _{rgbt}			15	ns	

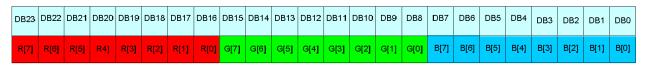
Note: Ta = -30 to 70 °C, IOVCC = 1.65V to 3.3V, VCI = 2.5V to 3.3V, AGND = DGND = 0V



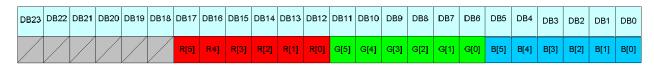


5.4.2 DPI Interface pixel format

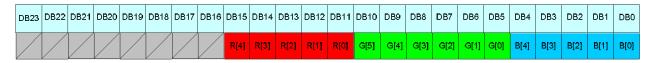
24-bit DPI interface connection (DB [23:0] is used): set pixel format DPI [2:0] = 3'h7



18-bit DPI interface connection (DB [17:0] is used): set pixel format DPI [2:0] = 3'h6



16-bit DPI interface connection (DB [15:0] is used): set pixel format DPI [2:0] = 3'h5



The Pixel clock (DOTCLK) runs all the time without stop. It is used to enter VSYNC, HSYNC, ENABLE and DB [23:0] states when there is a rising edge of the DOTCLK. The DOTCLK cannot be used as the internal clock for other functions of the display module.

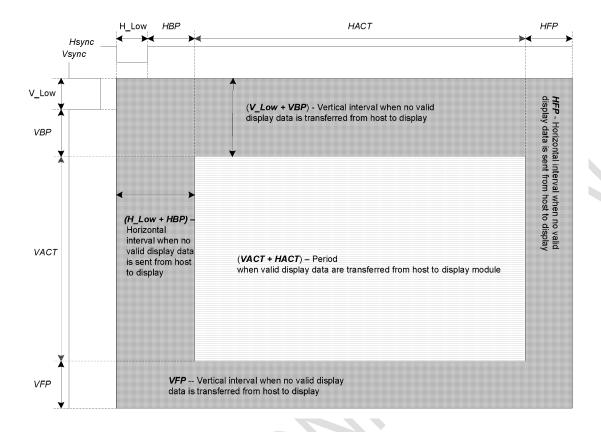
Vertical synchronization (VSYNC) is used to indicate when a new frame of the display is received. This is low enable and its state is read to the display module by a rising edge of the DOTCLK signal.

Horizontal synchronization (HSYNC) is used to indicate when a new line of the frame is received. This is low enable and its state is read to the display module by a rising edge of the DOTCLK signal.

Data Enable (ENABLE) is used to indicate when the RGB information that should be transferred in the display is received. This is a high enable, and its state is read to the display module by a rising edge of the DOTCLK signal. DB [23:0] is used to indicate what is the information of the image that is transferred on the display (when ENABLE = 0 (low) and there is a rising edge of DOTCLK). DB [23:0] can be 0 (low) or 1 (high). These lines are read by a rising edge of the DOTCLK signal. In RGB interface modes, the input display data is written to GRAM first then outputs the corresponding source voltage according to the gray data from GRAM.



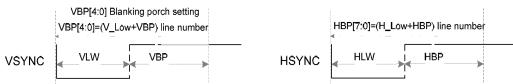
5.4.3 DPI(RGB) Interface timing



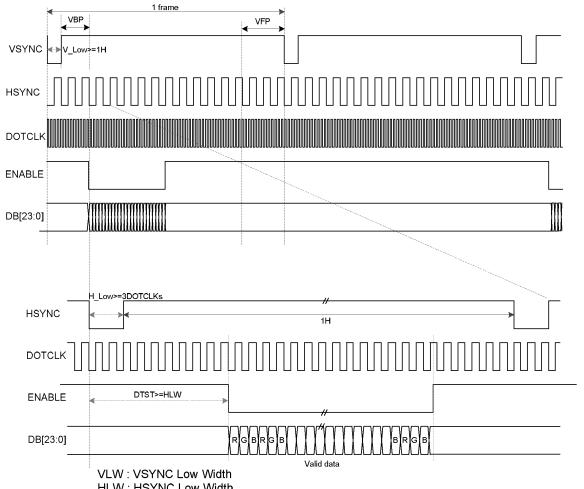
Parameters	Symbols	Min.	Тур.	Max.	Units
Horizontal Synchronization	H_Low	3	-		DOTCLK
Horizontal Back Porch	НВР	3	-	H_Low+HBP <192	DOTCLK
Horizontal Front Porch	HFP	3	-	255	DOTCLK
Horizontal Address	HACT	-	320	-	DOTCLK
Horizontal Frequency		-	-	33	KHz
Vertical Synchronization	V_Low	1	-		Line
Vertical Back Porch	VBP	2	-	V_Low+VBP+VFP < 32	Line
Vertical Front Porch	VFP	2	-		Line
Vertical Address	VACT	-	480	-	Line
Vertical Frequency		60	-	70	Hz
DOTCLK cycle		100	-	50	ns
DOTCLK Frequency		10	-	20	MHz

 $\label{eq:example:DOTCLK} \textbf{Example:DOTCLK} = 20 \text{Mhz}, \ \textbf{TE=70Hz}, \ \textbf{V_Low+VBP=2}, \ \textbf{VFP=2}, \ \textbf{H_Low+HBP=100}, \ \textbf{HFP=170}.$

Note: VBP[4:0]/HBP[7:0] (Blanking Porch Control, RB5h) define as follows:





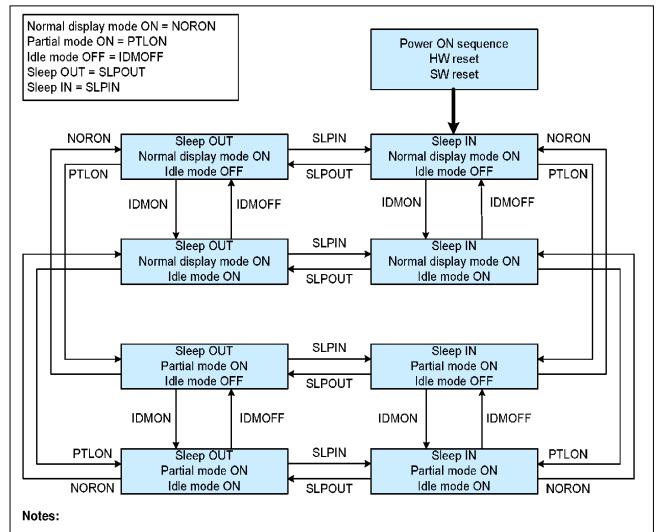


HLW: HSYNC Low Width

DTST: Data Transfer Startup Time



5.5 Power ON/OFF Sequence



- 1. There are not any abnormal visual effects when one power mode changes to another power mode.
- 2. There is not any limitation, which is not specified by users, when one power mode changes to another power mode.

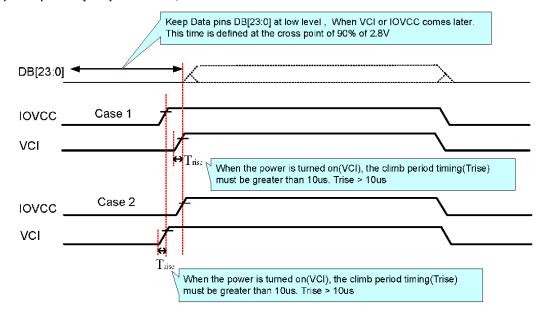




IOVCC and VCI can be applied or powered down in any order. During the Power Off sequence, if the LCD is in the Sleep Out mode, VCI and IOVCC must be powered down with a minimum of 120msec. If the LCD is in the Sleep In mode, VCI and IOVCC can be powered down with a minimum of 0msec after the RESX has been released. CSX can be applied at any time or can be permanently grounded. RESX has high priority over CSX.

Notes:

- 1. There will be no damage to the ILI9488 if the power sequences are not met.
- 2. There will be no abnormal visible effects on the display panel during the Power On/Off Sequence.
- 3. There will be no abnormal visible effects on the display between the end of the Power On Sequence and before receiving the Sleep Out command, and also between receiving the Sleep In command and the Power Off Sequence.
- 4. If the RESX line is not steadily held by the host during the Power On Sequence as defined in Sections 11.1 and 11.2, then it will be necessary to apply the Hardware Reset (RESX) after the completion of the Host Power On Sequence to ensure correct operations. Otherwise, all the functions are not guaranteed.
- 5. When the power is turned on, the climb period timing(Trise) must be greater than 10us.
- 6. Keep data pins DB[23:0] at low level, when VCI or IOVCC comes later





5.6 Reset timing

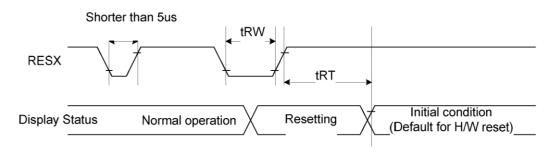


Table 39: Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
	tRW	Reset pulse duration	10		uS
RESX	tRT Reset cancel			5 (note 1,5)	mS
			120 (note 1,6,7)	mS	

Notes:

- The reset cancel also includes the required time for loading ID bytes, VCOM setting and other settings from the EEPROM to registers. After a rising edge of RESX, this loading is done within 5 ms after the H/W reset cancel (tRT).
- According to the Table 40, a spike due to an electrostatic discharge on the RESX line does not cause irregular system reset.

Table 40: Reset Description

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Reset period, the display will be blanked (When Reset starts in the Sleep Out mode, the display will enter the blanking sequence in at least 120 ms. The display remains the blank state in the Sleep In mode.) and then return to the default condition for the Hardware Reset.
- 4. Spike Rejection can also be applied during a valid reset pulse, as shown below:

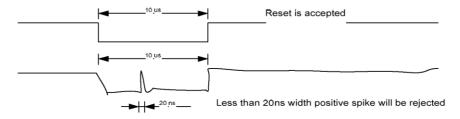


Figure 137: Positive Noise Pulse during Reset Low



6 Optical Characteristics

Item		Symbol	Condition	Min	Тур	Max	Unit	Remark
Minus Assertan		θТ		60	70			
		θВ	CR≧10	50	60		Dograd	Note2,3
View Angles		θL	UN = 10	60	70		Degree	Notez,5
		θR		60	70			
Contrast Ratio)	CR	θ=0°	400	500			Note 3
Response Tim	Δ.	T _{ON}	25 ℃		25	35	ms	Note 4
Nesponse IIII		T_{OFF}	25 (23	33	IIIS	
	White	x	-		0.286			Note 1,5
		у			0.304			
	Red	Х			0.608			Note 1,5
Chromaticity		у	Backlight is		0.336			
Omomationy	Green	Х	on		0.341			Note 1,5
	Orcen	у			0.604			14010 1,0
	Blue	х			0.146			Note 1,5
	Dide	у			0.073			14010 1,0
Uniformity		U			80		%	Note 6
NTSC					60		%	Note 5
Luminance		٦		250			cd/m ²	Note 7

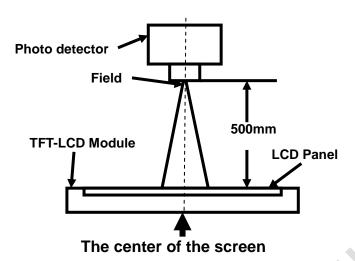
Test Conditions:

- 1. $I_F = 20$ mA, and the ambient temperature is 25°C.
- 2. The test systems refer to Note 1 and Note 2.



Note 1: Definition of optical measurement system.

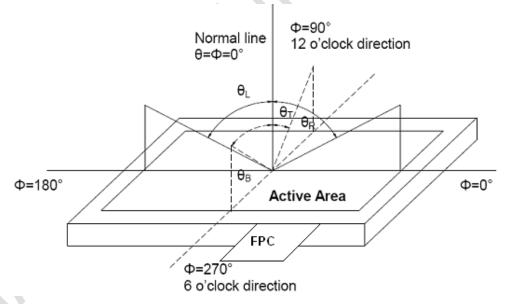
The optical characteristics should be measured in dark room. After 5 Minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Item	Photo detector	Field
Contrast Ratio		
Luminance	SR-3A	1°
Chromaticity	SR-SA	
Lum Uniformity		
Response Time	BM-7A	2°

Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



Note 3: Definition of contrast ratio

 $Contrast \ ratio \ (CR) = \frac{Luminance \ measured \ when \ LCD \ is \ on \ the \ "White" \ state}{Luminance \ measured \ when \ LCD \ is \ on \ the \ "Black" \ state}$

"White state ": The state is that the LCD should drive by Vwhite.

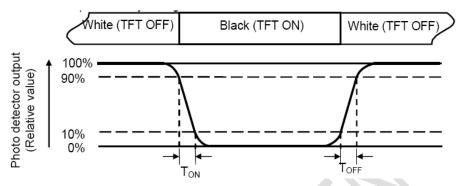
"Black state": The state is that the LCD should drive by Vblack.



Vwhite: To be determined Vblack: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

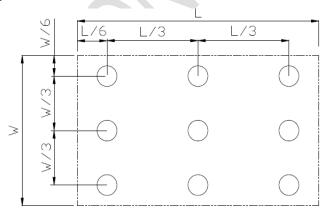
Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = Lmin/Lmax

L----- Active area length W---- Active area width



Lmax: The measured Maximum luminance of all measurement position.

Lmin: The measured Minimum luminance of all measurement position.

Note 7: Definition of Luminance:

Measure the luminance of white state at center point.



7 Environmental / Reliability Test

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts=+70℃, 240hrs	Note1 IEC60068-2-1,GB2423.2
2	Low Temperature Operation	Ta=-20℃, 240hrs	IEC60068-2-1 GB2423.1
3	High Temperature Storage	Ta=+80°C, 240hrs	IEC60068-2-1 GB2423.1
4	Low Temperature Storage	Ta=-30℃, 240hrs	IEC60068-2-1 GB2423.1
5	High Temperature and Humidity Operation	Ta=+60°C, 90% RH 240 hours	Note2 IEC60068-2-78 GB/T2423.3
6	Thermal Shock (non-operation)	-30°C 30 min~+70°C 30 min, Change time:5min, 20 Cycles	Start with cold temperature, End with high temperature, IEC60068-2-14,GB2423.22
7	Electro Static Discharge (Operation)	C=150pF, R=330 , 5points/panel Air: \pm 8KV, 5times; Contact: \pm 4KV, 5 times; (Environment: 15° C \sim 35 $^{\circ}$ C, 30% \sim 60%, 86Kpa \sim 106Kpa)	IEC61000-4-2 GB/T17626.2
8	Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition)	IEC60068-2-6 GB/T2423.10
9	Shock (Non-operation)	60G 6ms, ±X,±Y,±Z 3times, for each direction	IEC60068-2-27 GB/T2423.5
10	Package Drop Test	Height:80 cm, 1 corner, 3 edges, 6 surfaces	IEC60068-2-32 GB/T2423.8

Note1: Ts is the temperature of panel's surface.

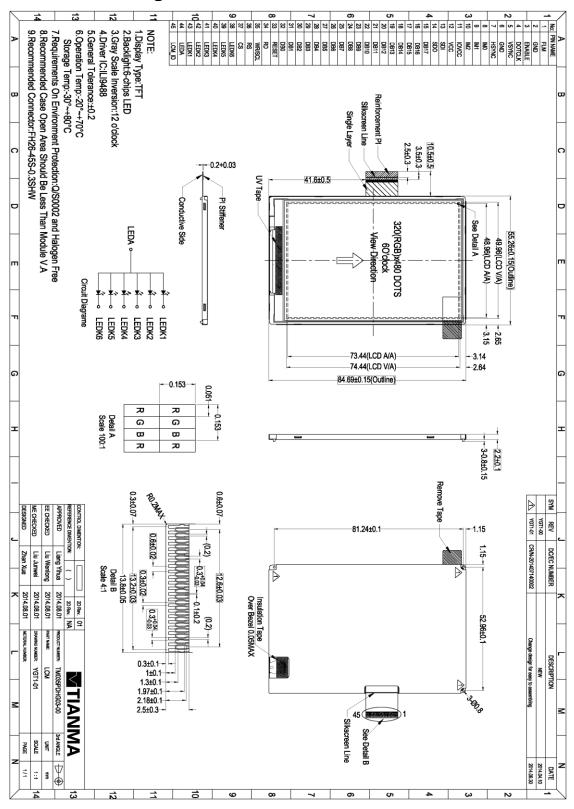
Note2: Ta is the ambient temperature of sample.

Note3: Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.

Note 4: In the standard condition, there shall be no practical problem that may affect the display function. After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.



8 Mechanical Drawing

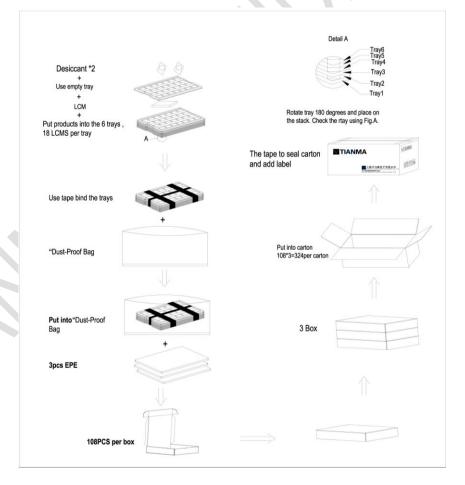




9 Packing Drawing

Per Carton

No	Item	Model (Material)	Dimensions(mm)	Unit Weight(Kg)	Quantity	Remark		
1	LCM module	TM035PDHG03-00	55.26*84.69*2.2	0.021	324			
2	Tray	PET(Transmit)	485x330x13	0.117	21	Anti-static		
3	EPE	EPE	485×330×5	0.083	9			
4	Desiccant	Desiccant	45X35	0.002	6			
5	Dust-Proof Bag	PE	700×545	0.046	3			
6	Box	Corrugated Paper	520×345×74	0.3879	3			
7	Carton	Corrugated Paper	544×365×250	1.01	1			
8	Total weight	12.45±5% Kg						





10 Precautions for Use of LCD Modules

- 10.6 Handling Precautions
- 10.6.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 10.6.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 10.6.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 10.6.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 10.6.5 If the display surface is contaMinated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
 - Isopropyl alcohol
 - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 10.6.6 Do not attempt to disassemble the LCD Module.
- 10.6.7 If the logic circuit power is off, do not apply the input signals.
- 10.6.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - 10.1.8.1 Be sure to ground the body when handling the LCD Modules.
 - 10.1.8.2 Tools required for assembly, such as soldering irons, must be properly ground.
- 10.1.8.3 To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- 10.1.8.4 The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.
- 10.7 Storage precautions
 - 10.7.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 10.7.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:
- Temperature : 0° C $\sim 40^{\circ}$ C Relatively humidity: $\leq 80\%$
 - 10.7.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
- 10.8 Transportation Precautions
 - 10.8.1 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.